



## **SPECIFICATION**

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL10C101JB8NNNL
- Description : CAP, 100pF, 50V, ±5%, C0G, 0603

A. Samsung Part Number

|                          | <u>CL</u> <u>10</u> <u>C</u><br>① ② ③ | 101         J         B         8         N         N           ④         5         6         7         8         9 | <u>N</u> <u>L</u><br>100 11 |
|--------------------------|---------------------------------------|---|-----------------------------|
| 1 Series                 | Samsung Multi-layer Ceramic Capacitor |   |                             |
| <ol> <li>Size</li> </ol> | 0603 (inch code)                      | L: 1.6 ± 0.1 mm   | W: 0.8 ± 0.1 mm             |
| ③ Dielectric             | C0G                                   | Inner electrode   | Ni                          |
| ④ Capacitance            | <b>100</b> pF                         | Termination   | Cu                          |
| <b>⑤</b> Capacitance     | ±5 %                                  | Plating   | Sn 100% (Pb Free)           |
| tolerance                |                                       | 9 Product   | Normal                      |
| Rated Voltage            | 50 V                                  | 10 Special  | Reserved for future use     |
| ⑦ Thickness              | 0.8 ± 0.1 mm                          | ① Packaging   | Cardboard Type, 13" reel    |

## B. Samsung Reliablility Test and Judgement condition

|                   | Performance  | Test condition                       |  |
|-------------------|--|--------------------------------------|--|
| Capacitance       | Within specified tolerance   | 1M±±10% 0.5~5Vrms                    |  |
| Q                 | 1000 min   |                                      |  |
| Insulation        | 10,000Mohm or 500Mohm⋅ <i>μ</i> F  | Rated Voltage 60~120 sec.            |  |
| Resistance        | Whichever is Smaller   |                                      |  |
| Appearance        | No abnormal exterior appearance  | Microscope (×10)                     |  |
| Withstanding      | No dielectric breakdown or   | 300% of the rated voltage            |  |
| Voltage           | mechanical breakdown   |                                      |  |
| Temperature       | COG  |                                      |  |
| Characterisitcs   | (From -55 $^\circ\!\!\mathbb{C}$ to 125 $^\circ\!\!\mathbb{C}$ , Capacitance change shoud be within ±30PPM/ $^\circ\!\!\mathbb{C}$ ) |                                      |  |
| Adhesive Strength | No peeling shall be occur on the   | 500g·F, for 10±1 sec.                |  |
| of Termination    | terminal electrode   |                                      |  |
| Bending Strength  | Capacitance change :   | Bending to the limit (1mm)           |  |
|                   | within $\pm 5\%$ or $\pm 0.5$ pF whichever is larger   | with 1.0mm/sec.                      |  |
| Solderability     | More than 75% of terminal surface  | SnAg3.0Cu0.5 solder                  |  |
|                   | is to be soldered newly  | 245±5℃, 3±0.3sec.                    |  |
|                   |  | (preheating : 80~120℃ for 10~30sec.) |  |
| Resistance to     | Capacitance change :   | Solder pot : 270±5℃, 10±1sec.        |  |
| Soldering heat    | within $\pm 2.5\%$ or $\pm 0.25$ pF whichever is larger  |                                      |  |
|                   | Tan δ, IR : initial spec.  |                                      |  |

|                  | Performance   | Test condition   |
|------------------|---|--|
| Vibration Test   | Capacitance change :                                      | Amplitude : 1.5mm  |
|                  | within $\pm 2.5\%$ or $\pm 0.25_{pF}$ whichever is larger | From 10H₂ to 55H₂ (return : 1min.)                           |
|                  | Tan δ, IR : initial spec.                                 | 2hours $\times$ 3 direction (x, y, z)                        |
| Moisture         | Capacitance change :                                      | With rated voltage   |
| Resistance       | within $\pm 7.5\%$ or $\pm 0.75$ pF whichever is larger   | 40±2℃, 90~95%RH, 500+12/-0hrs                                |
|                  | Q : 200 min   |  |
|                  | IR : 500Mohm or 25Mohm $\cdot \mu F$                      |  |
|                  | Whichever is Smaller                                      |  |
| High Temperature | Capacitance change :                                      | With 200% of the rated voltage                               |
| Resistance       | within $\pm 3\%$ or $\pm 0.3$ pF whichever is larger      | Max. operating temperature                                   |
|                  | Q : 350 min   | 1000+48/-0hrs  |
|                  | IR : 1000Mohm or 50Mohm $\cdot \mu F$                     |  |
|                  | Whichever is Smaller                                      |  |
| Temperature      | Capacitance change :                                      | 1 cycle condition  |
| Cycling          | within $\pm 2.5\%$ or $\pm 0.25$ pF whichever is larger   | Min. operating temperature $\rightarrow$ 25 °C               |
|                  | Tan δ, IR : initial spec.                                 | $\rightarrow$ Max. operating temperature $\rightarrow$ 25 °C |
|                  |   |  |
|                  |   |  |
|                  |   | 5 cycle test   |

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max )

\* For the more detail Specification, Please refer to the Samsung MLCC catalogue.